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# DDR2 SDRAM SODIMM

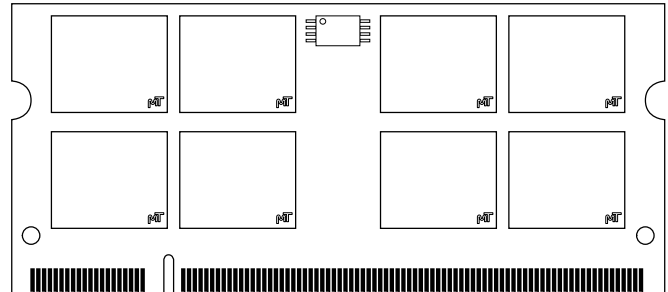
**MT16HTF12864HY – 1GB**
**MT16HTF25664HY – 2GB**

## Features

- 200-pin, small-outline dual in-line memory module (SODIMM)
- Fast data transfer rates: PC2-3200, PC2-4200, PC2-5300, or PC2-6400
- 1GB (128 Meg x 64) or 2GB (256 Meg x 64)
- $V_{DD} = V_{DDQ} 1.8V$
- $V_{DDSPD} = 1.7\text{--}3.6V$
- JEDEC-standard 1.8V I/O (SSTL\_18-compatible)
- Differential data strobe (DQS, DQS#) option
- 4n-bit prefetch architecture
- Multiple internal device banks for concurrent operation
- Programmable CAS latency (CL)
- Posted CAS additive latency (AL)
- WRITE latency = READ latency - 1 t<sub>CK</sub>
- Programmable burst lengths (BL): 4 or 8
- Adjustable data-output drive strength
- 64ms, 8192-cycle refresh
- On-die termination (ODT)
- Serial presence detect (SPD) with EEPROM
- Gold edge contacts
- Dual rank

**Figure 1: 200-Pin SODIMM (MO-224 R/C E)**

Module height: 30mm (1.18in)



## Options

- Operating temperature
  - Commercial ( $0^{\circ}C \leq T_A \leq +70^{\circ}C$ )
  - Industrial ( $-40^{\circ}C \leq T_A \leq +85^{\circ}C$ )<sup>1</sup>
- Package
  - 200-pin DIMM (lead-free)
- Frequency/CL<sup>2</sup>
  - 2.5ns @ CL = 5 (DDR2-800)
  - 2.5ns @ CL = 6 (DDR2-800)
  - 3ns @ CL = 5 (DDR2-667)
  - 3.75ns @ CL = 4 (DDR2-533)
  - 5.0ns @ CL = 3 (DDR2-400)<sup>3</sup>

## Marking

None
I
Y
-80E
-800
-667
-53E
-40E

- Notes:
1. Contact Micron for industrial temperature module offerings.
  2. CL = CAS (READ) latency.
  3. Not recommended for new designs.

**Table 1: Key Timing Parameters**

Speed Grade	Industry Nomenclature	Data Rate (MT/s)				t <sub>RCD</sub> (ns)	t <sub>RP</sub> (ns)	t <sub>RC</sub> (ns)
		CL = 6	CL = 5	CL = 4	CL = 3			
-80E	PC2-6400	800	800	533	400	12.5	12.5	55
-800	PC2-6400	800	667	533	400	15	15	55
-667	PC2-5300	–	667	553	400	15	15	55
-53E	PC2-4200	–	–	553	400	15	15	55
-40E	PC2-3200	–	–	400	400	15	15	55



**Table 2: Addressing**

Parameter	1GB	2GB
Refresh count	8K	8K
Row address	16K A[13:0]	16K A[13:0]
Device bank address	4 BA[1:0]	8 BA[2:0]
Device configuration	512Mb (64 Meg x 8)	1Gb (128 Meg x 8)
Column address	1K A[9:0]	1K A[9:0]
Module rank address	2 S#[1:0]	2 S#[1:0]

**Table 3: Part Numbers and Timing Parameters – 1GB Modules**

Base device: MT47H64M8,<sup>1</sup> 512Mb DDR2 SDRAM

Part Number <sup>2</sup>	Module Density	Configuration	Module Bandwidth	Memory Clock/ Data Rate	Clock Cycles (CL- <sup>t</sup> RCD- <sup>t</sup> RP)
MT16HTF12864H(I)Y-80E__	1GB	128 Meg x 64	6.4 GB/s	2.5ns/800 MT/s	5-5-5
MT16HTF12864H(I)Y-800__	1GB	128 Meg x 64	6.4 GB/s	2.5ns/800 MT/s	6-6-6
MT16HTF12864H(I)Y-667__	1GB	128 Meg x 64	5.3 GB/s	3.0ns/667 MT/s	5-5-5
MT16HTF12864H(I)Y-53E__	1GB	128 Meg x 64	4.3 GB/s	3.75ns/533 MT/s	4-4-4
MT16HTF12864H(I)Y-40E__	1GB	128 Meg x 64	3.2 GB/s	5.0ns/400 MT/s	3-3-3

**Table 4: Part Numbers and Timing Parameters – 2GB Modules**

Base device: MT47H128M8,<sup>1</sup> 1Gb DDR2 SDRAM

Part Number <sup>2</sup>	Module Density	Configuration	Module Bandwidth	Memory Clock/ Data Rate	Clock Cycles (CL- <sup>t</sup> RCD- <sup>t</sup> RP)
MT16HTF25664H(I)Y-80E__	2GB	256 Meg x 64	6.4 GB/s	2.5ns/800 MT/s	5-5-5
MT16HTF25664H(I)Y-800__	2GB	256 Meg x 64	6.4 GB/s	2.5ns/800 MT/s	6-6-6
MT16HTF25664H(I)Y-667__	2GB	256 Meg x 64	5.3 GB/s	3.0ns/667 MT/s	5-5-5
MT16HTF25664H(I)Y-53E__	2GB	256 Meg x 64	4.3 GB/s	3.75ns/533 MT/s	4-4-4
MT16HTF25664H(I)Y-40E__	2GB	256 Meg x 64	3.2 GB/s	5.0ns/400 MT/s	3-3-3

- Notes:
1. The data sheet for the base device can be found on Micron’s Web site.
  2. All part numbers end with a two-place code (not shown) that designates component and PCB revisions. Consult factory for current revision codes. Example: MT16HTF12864HY-40ED1.



## Pin Assignments

Table 5: Pin Assignments

200-Pin DDR2 SODIMM Front								200-Pin DDR2 SODIMM Back							
Pin	Symbol	Pin	Symbol	Pin	Symbol	Pin	Symbol	Pin	Symbol	Pin	Symbol	Pin	Symbol	Pin	Symbol
1	V <sub>REF</sub>	51	DQS2	101	A1	151	DQ42	2	V <sub>SS</sub>	52	DM2	102	A0	152	DQ46
3	V <sub>SS</sub>	53	V <sub>SS</sub>	103	V <sub>DD</sub>	153	DQ43	4	DQ4	54	V <sub>SS</sub>	104	V <sub>DD</sub>	154	DQ47
5	DQ0	55	DQ18	105	A10	155	V <sub>SS</sub>	6	DQ5	56	DQ22	106	BA1	156	V <sub>SS</sub>
7	DQ1	57	DQ19	107	BA0	157	DQ48	8	V <sub>SS</sub>	58	DQ23	108	RAS#	158	DQ52
9	V <sub>SS</sub>	59	V <sub>SS</sub>	109	WE#	159	DQ49	10	DM0	60	V <sub>SS</sub>	110	S0#	160	DQ53
11	DQS0#	61	DQ24	111	V <sub>DD</sub>	161	V <sub>SS</sub>	12	V <sub>SS</sub>	62	DQ28	112	V <sub>DD</sub>	162	V <sub>SS</sub>
13	DQS0	63	DQ25	113	CAS#	163	NC	14	DQ6	64	DQ29	114	ODT0	164	CK1
15	V <sub>SS</sub>	65	V <sub>SS</sub>	115	S1#	165	V <sub>SS</sub>	16	DQ7	66	V <sub>SS</sub>	116	A13	166	CK1#
17	DQ2	67	DM3	117	V <sub>DD</sub>	167	DQS6#	18	V <sub>SS</sub>	68	DQS3#	118	V <sub>DD</sub>	168	V <sub>SS</sub>
19	DQ3	69	NC	119	ODT1	169	DQS6	20	DQ12	70	DQS3	120	NC	170	DM6
21	V <sub>SS</sub>	71	V <sub>SS</sub>	121	V <sub>SS</sub>	171	V <sub>SS</sub>	22	DQ13	72	V <sub>SS</sub>	122	V <sub>SS</sub>	172	V <sub>SS</sub>
23	DQ8	73	DQ26	123	DQ32	173	DQ50	24	V <sub>SS</sub>	74	DQ30	124	DQ36	174	DQ54
25	DQ9	75	DQ27	125	DQ33	175	DQ51	26	DM1	76	DQ31	126	DQ37	176	DQ55
27	V <sub>SS</sub>	77	V <sub>SS</sub>	127	V <sub>SS</sub>	177	V <sub>SS</sub>	28	V <sub>SS</sub>	78	V <sub>SS</sub>	128	V <sub>SS</sub>	178	V <sub>SS</sub>
29	DQS1#	79	CKE0	129	DQS4#	179	DQ56	30	CK0	80	CKE1	130	DM4	180	DQ60
31	DQS1	81	V <sub>DD</sub>	131	DQS4	181	DQ57	32	CK0#	82	V <sub>DD</sub>	132	V <sub>SS</sub>	182	DQ61
33	V <sub>SS</sub>	83	NC	133	V <sub>SS</sub>	183	V <sub>SS</sub>	34	V <sub>SS</sub>	84	NC	134	DQ38	184	V <sub>SS</sub>
35	DQ10	85	NC/BA2 <sup>1</sup>	135	DQ34	185	DM7	36	DQ14	86	NC	136	DQ39	186	DQS7#
37	DQ11	V <sub>DD</sub>	V <sub>DD</sub>	137	DQ35	187	V <sub>SS</sub>	38	DQ15	88	V <sub>DD</sub>	138	V <sub>SS</sub>	188	DQS7
39	V <sub>SS</sub>	89	A12	139	V <sub>SS</sub>	189	DQ58	40	V <sub>SS</sub>	90	A11	140	DQ44	190	V <sub>SS</sub>
41	V <sub>SS</sub>	91	A9	141	DQ40	191	DQ59	42	V <sub>SS</sub>	92	A7	142	DQ45	192	DQ62
43	DQ16	93	A8	143	DQ41	193	V <sub>SS</sub>	44	DQ20	94	A6	144	V <sub>SS</sub>	194	DQ63
45	DQ17	95	V <sub>DD</sub>	145	V <sub>SS</sub>	195	SDA	46	DQ21	96	V <sub>DD</sub>	146	DQS5#	196	V <sub>SS</sub>
47	V <sub>SS</sub>	97	A5	147	DM5	197	SCL	48	V <sub>SS</sub>	98	A4	148	DQS5	198	SA0
49	DQS2#	99	A3	149	V <sub>SS</sub>	199	V <sub>DDSPD</sub>	50	NC	100	A2	150	V <sub>SS</sub>	200	SA1

Note: 1. Pin 85 is NC for 1GB and BA2 for 2GB.

## Pin Descriptions

The pin description table below is a comprehensive list of all possible pins for all DDR2 modules. All pins listed may not be supported on this module. See Pin Assignments for information specific to this module.

**Table 6: Pin Descriptions**

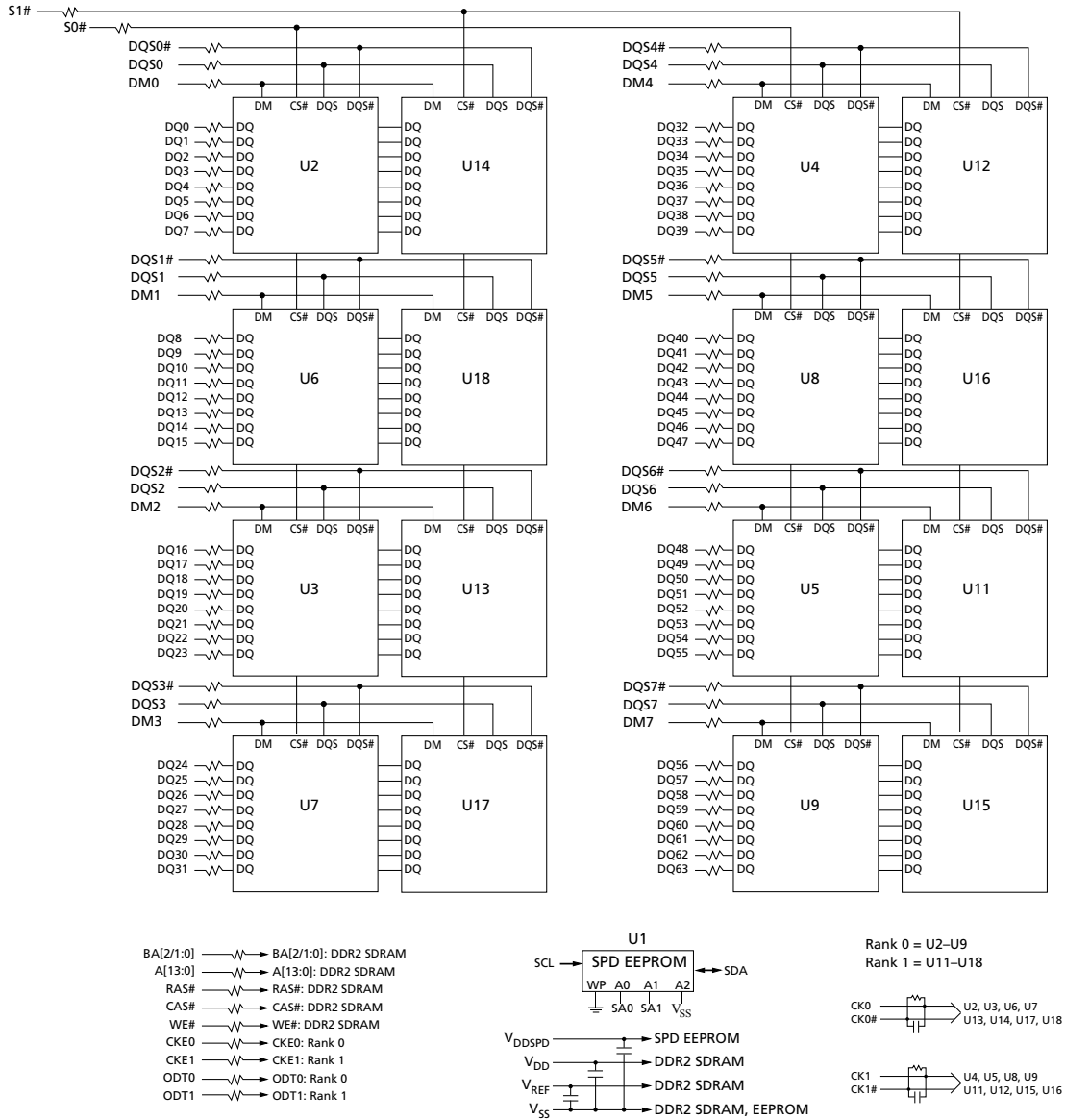
Symbol	Type	Description
Ax	Input	<b>Address inputs:</b> Provide the row address for ACTIVE commands, and the column address and auto precharge bit (A10) for READ/WRITE commands, to select one location out of the memory array in the respective bank. A10 sampled during a PRECHARGE command determines whether the PRECHARGE applies to one bank (A10 LOW, bank selected by BAx) or all banks (A10 HIGH). The address inputs also provide the op-code during a LOAD MODE command. See the Pin Assignments Table for density-specific addressing information.
BAx	Input	<b>Bank address inputs:</b> Define the device bank to which an ACTIVE, READ, WRITE, or PRECHARGE command is being applied. BA define which mode register (MR0, MR1, MR2, and MR3) is loaded during the LOAD MODE command.
CKx, CK#x	Input	<b>Clock:</b> Differential clock inputs. All control, command, and address input signals are sampled on the crossing of the positive edge of CK and the negative edge of CK#.
CKEx	Input	<b>Clock enable:</b> Enables (registered HIGH) and disables (registered LOW) internal circuitry and clocks on the DDR2 SDRAM.
DMx,	Input	<b>Data mask (x8 devices only):</b> DM is an input mask signal for write data. Input data is masked when DM is sampled HIGH, along with that input data, during a write access. Although DM pins are input-only, DM loading is designed to match that of the DQ and DQS pins.
ODTx	Input	<b>On-die termination:</b> Enables (registered HIGH) and disables (registered LOW) termination resistance internal to the DDR2 SDRAM. When enabled in normal operation, ODT is only applied to the following pins: DQ, DQS, DQS#, DM, and CB. The ODT input will be ignored if disabled via the LOAD MODE command.
Par_In	Input	<b>Parity input:</b> Parity bit for Ax, RAS#, CAS#, and WE#.
RAS#, CAS#, WE#	Input	<b>Command inputs:</b> RAS#, CAS#, and WE# (along with S#) define the command being entered.
RESET#	Input	<b>Reset:</b> Asynchronously forces all registered outputs LOW when RESET# is LOW. This signal can be used during power-up to ensure that CKE is LOW and DQ are High-Z.
S#x	Input	<b>Chip select:</b> Enables (registered LOW) and disables (registered HIGH) the command decoder.
SAx	Input	<b>Serial address inputs:</b> Used to configure the SPD EEPROM address range on the I <sup>2</sup> C bus.
SCL	Input	<b>Serial clock for SPD EEPROM:</b> Used to synchronize communication to and from the SPD EEPROM on the I <sup>2</sup> C bus.
CBx	I/O	<b>Check bits.</b> Used for system error detection and correction.
DQx	I/O	<b>Data input/output:</b> Bidirectional data bus.
DQSx, DQS#x	I/O	<b>Data strobe:</b> Travels with the DQ and is used to capture DQ at the DRAM or the controller. Output with read data; input with write data for source synchronous operation. DQS# is only used when differential data strobe mode is enabled via the LOAD MODE command.

**Table 6: Pin Descriptions (Continued)**

Symbol	Type	Description
SDA	I/O	<b>Serial data:</b> Used to transfer addresses and data into and out of the SPD EEPROM on the I <sup>2</sup> C bus.
RDQSx, RDQS#x	Output	<b>Redundant data strobe (x8 devices only):</b> RDQS is enabled/disabled via the LOAD MODE command to the extended mode register (EMR). When RDQS is enabled, RDQS is output with read data only and is ignored during write data. When RDQS is disabled, RDQS becomes data mask (see DMx). RDQS# is only used when RDQS is enabled and differential data strobe mode is enabled.
Err_Out#	Output (open drain)	<b>Parity error output:</b> Parity error found on the command and address bus.
V <sub>DD</sub> /V <sub>DDQ</sub>	Supply	<b>Power supply:</b> 1.8V ±0.1V. The component V <sub>DD</sub> and V <sub>DDQ</sub> are connected to the module V <sub>DD</sub> .
V <sub>DDSPD</sub>	Supply	<b>SPD EEPROM power supply:</b> 1.7–3.6V.
V <sub>REF</sub>	Supply	<b>Reference voltage:</b> V <sub>DD</sub> /2.
V <sub>SS</sub>	Supply	Ground.
NC	–	<b>No connect:</b> These pins are not connected on the module.
NF	–	<b>No function:</b> These pins are connected within the module, but provide no functionality.
NU	–	<b>Not used:</b> These pins are not used in specific module configurations/operations.
RFU	–	Reserved for future use.

## Functional Block Diagram

Figure 2: Functional Block Diagram



## General Description

DDR2 SDRAM modules are high-speed, CMOS dynamic random access memory modules that use internally configured 4 or 8-bank DDR2 SDRAM devices. DDR2 SDRAM modules use DDR architecture to achieve high-speed operation. DDR2 architecture is essentially a  $4n$ -prefetch architecture with an interface designed to transfer two data words per clock cycle at the I/O pins. A single read or write access for the DDR2 SDRAM module effectively consists of a single  $4n$ -bit-wide, one-clock-cycle data transfer at the internal DRAM core and eight corresponding  $n$ -bit-wide, one-half-clock-cycle data transfers at the I/O pins.

DDR2 modules use two sets of differential signals: DQS, DQS# to capture data and CK and CK# to capture commands, addresses, and control signals. Differential clocks and data strobes ensure exceptional noise immunity for these signals and provide precise crossing points to capture input signals. A bidirectional data strobe (DQS, DQS#) is transmitted externally, along with data, for use in data capture at the receiver. DQS is a strobe transmitted by the DDR2 SDRAM device during READs and by the memory controller during WRITEs. DQS is edge-aligned with data for READs and center-aligned with data for WRITEs.

DDR2 SDRAM modules operate from a differential clock (CK and CK#); the crossing of CK going HIGH and CK# going LOW will be referred to as the positive edge of CK. Commands (address and control signals) are registered at every positive edge of CK. Input data is registered on both edges of DQS, and output data is referenced to both edges of DQS, as well as to both edges of CK.

## Serial Presence-Detect EEPROM Operation

DDR2 SDRAM modules incorporate serial presence-detect. The SPD data is stored in a 256-byte EEPROM. The first 128 bytes are programmed by Micron to identify the module type and various SDRAM organizations and timing parameters. The remaining 128 bytes of storage are available for use by the customer. System READ/WRITE operations between the master (system logic) and the slave EEPROM device occur via a standard I<sup>2</sup>C bus using the DIMM's SCL (clock) SDA (data), and SA (address) pins. Write protect (WP) is connected to V<sub>SS</sub>, permanently disabling hardware write protection.





## Electrical Specifications

Stresses greater than those listed may cause permanent damage to the module. This is a stress rating only, and functional operation of the module at these or any other conditions outside those indicated in the device data sheet are not implied. Exposure to absolute maximum rating conditions for extended periods may adversely affect reliability.

**Table 7: Absolute Maximum Ratings**

Symbol	Parameter	Min	Max	Units	
$V_{DD}$	$V_{DD}$ supply voltage relative to $V_{SS}$	-1.0	2.3	V	
$V_{IN}, V_{OUT}$	Voltage on any pin relative to $V_{SS}$	-0.5	2.3	V	
$I_I$	Input leakage current; Any input $0V \leq V_{IN} \leq V_{DD}$ ; $V_{REF}$ input $0V \leq V_{IN} \leq 0.95V$ ; (All other pins not under test = $0V$ )	Address inputs, RAS#, CAS#, WE#	-80	80	$\mu A$
		S#, CKE, ODT, CK, CK#	-40	40	
		DM	-10	10	
$I_{OZ}$	Output leakage current; $0V \leq V_{OUT}$ ; DQ and ODT are disabled	-10	10	$\mu A$	
$I_{VREF}$	$V_{REF}$ leakage current; $V_{REF}$ = valid $V_{REF}$ level	-32	32	$\mu A$	
$T_A$	Module ambient operating temperature	Commercial	0	70	$^{\circ}C$
		Industrial	-40	85	$^{\circ}C$
$T_C^1$	DDR2 SDRAM component operating temperature <sup>2</sup>	Commercial	0	85	$^{\circ}C$
		Industrial	-40	95	$^{\circ}C$

- Notes:
1. The refresh rate is required to double when  $T_C$  exceeds  $85^{\circ}C$ .
  2. For further information, refer to technical note TN-00-08: "Thermal Applications," available on Micron's Web site.



## DRAM Operating Conditions

Recommended AC operating conditions are given in the DDR2 component data sheets. Component specifications are available on Micron's Web site. Module speed grades correlate with component speed grades.

**Table 8: Module and Component Speed Grades**

DDR2 components may exceed the listed module speed grades; module may not be available in all listed speed grades

Module Speed Grade	Component Speed Grade
-1GA	-187E
-80E	-25E
-800	-25
-667	-3
-53E	-37E
-40E	-5E

## Design Considerations

### Simulations

Micron memory modules are designed to optimize signal integrity through carefully designed terminations, controlled board impedances, routing topologies, trace length matching, and decoupling. However, good signal integrity starts at the system level. Micron encourages designers to simulate the signal characteristics of the system's memory bus to ensure adequate signal integrity of the entire memory system.

### Power

Operating voltages are specified at the DRAM, not at the edge connector of the module. Designers must account for any system voltage drops at anticipated power levels to ensure the required supply voltage is maintained.



## I<sub>DD</sub> Specifications

**Table 9: DDR2 I<sub>DD</sub> Specifications and Conditions – 1GB**

Values shown for MT47H64M8 DDR2 SDRAM only and are computed from values specified in the 512Mb (64 Meg x 8) component data sheet

Parameter	Symbol	-80E/ -800	-667	-53E	-40E	Units	
<b>Operating one bank active-precharge current:</b> $t_{CK} = t_{CK} (I_{DD})$ , $t_{RC} = t_{RC} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MIN} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are switching; Data bus inputs are switching	I <sub>DD0</sub> <sup>1</sup>	856	776	696	696	mA	
<b>Operating one bank active-read-precharge current:</b> I <sub>OUT</sub> = 0mA; BL = 4, CL = CL (I <sub>DD</sub> ), AL = 0; $t_{CK} = t_{CK} (I_{DD})$ , $t_{RC} = t_{RC} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MIN} (I_{DD})$ , $t_{RCD} = t_{RCD} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are switching; Data pattern is same as I <sub>DD4W</sub>	I <sub>DD1</sub> <sup>1</sup>	976	896	816	776	mA	
<b>Precharge power-down current:</b> All device banks idle; $t_{CK} = t_{CK} (I_{DD})$ ; CKE is LOW; Other control and address bus inputs are stable; Data bus inputs are floating	I <sub>DD2P</sub> <sup>2</sup>	112	112	112	112	mA	
<b>Precharge quiet standby current:</b> All device banks idle; $t_{CK} = t_{CK} (I_{DD})$ ; CKE is HIGH, S# is HIGH; Other control and address bus inputs are stable; Data bus inputs are floating	I <sub>DD2Q</sub> <sup>2</sup>	800	720	640	560	mA	
<b>Precharge standby current:</b> All device banks idle; $t_{CK} = t_{CK} (I_{DD})$ ; CKE is HIGH, S# is HIGH; Other control and address bus inputs are switching; Data bus inputs are switching	I <sub>DD2N</sub> <sup>2</sup>	880	800	720	640	mA	
<b>Active power-down current:</b> All device banks open; $t_{CK} = t_{CK} (I_{DD})$ ; CKE is LOW; Other control and address bus inputs are stable; Data bus inputs are floating	Fast PDN exit MR[12] = 0	I <sub>DD3P</sub> <sup>2</sup>	640	560	480	400	mA
		Slow PDN exit MR[12] = 1	192	192	192	192	
<b>Active standby current:</b> All device banks open; $t_{CK} = t_{CK} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MAX} (I_{DD})$ , $t_{RP} = t_{RP} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Other control and address bus inputs are switching; Data bus inputs are switching	I <sub>DD3N</sub> <sup>2</sup>	1120	1040	880	720	mA	
<b>Operating burst write current:</b> All device banks open; Continuous burst writes; BL = 4, CL = CL (I <sub>DD</sub> ), AL = 0; $t_{CK} = t_{CK} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MAX} (I_{DD})$ , $t_{RP} = t_{RP} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are switching; Data bus inputs are switching	I <sub>DD4W</sub> <sup>1</sup>	1616	1416	1176	976	mA	
<b>Operating burst read current:</b> All device banks open; Continuous burst read, I <sub>OUT</sub> = 0mA; BL = 4, CL = CL (I <sub>DD</sub> ), AL = 0; $t_{CK} = t_{CK} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MAX} (I_{DD})$ , $t_{RP} = t_{RP} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are switching; Data bus inputs are switching	I <sub>DD4R</sub> <sup>1</sup>	1696	1496	1216	976	mA	
<b>Burst refresh current:</b> $t_{CK} = t_{CK} (I_{DD})$ ; REFRESH command at every $t_{RFC} (I_{DD})$ interval; CKE is HIGH, S# is HIGH between valid commands; Other control and address bus inputs are switching; Data bus inputs are switching	I <sub>DD5</sub> <sup>2</sup>	3680	2880	2720	2640	mA	
<b>Self refresh current:</b> CK and CK# at 0V; CKE ≤ 0.2V; Other control and address bus inputs are floating; Data bus inputs are floating	I <sub>DD6</sub> <sup>2</sup>	112	112	112	112	mA	



**Table 9: DDR2 I<sub>DD</sub> Specifications and Conditions – 1GB (Continued)**

Values shown for MT47H64M8 DDR2 SDRAM only and are computed from values specified in the 512Mb (64 Meg x 8) component data sheet

Parameter	Symbol	-80E/ -800	-667	-53E	-40E	Units
<b>Operating bank interleave read current:</b> All device banks interleaving reads; I <sub>OUT</sub> = 0mA; BL = 4, CL = CL (I <sub>DD</sub> ), AL = <sup>t</sup> RCD (I <sub>DD</sub> ) - 1 × <sup>t</sup> CK (I <sub>DD</sub> ); <sup>t</sup> CK = <sup>t</sup> CK (I <sub>DD</sub> ), <sup>t</sup> RC = <sup>t</sup> RC (I <sub>DD</sub> ), <sup>t</sup> RRD = <sup>t</sup> RRD (I <sub>DD</sub> ), <sup>t</sup> RCD = <sup>t</sup> RCD (I <sub>DD</sub> ); CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are stable during deselects; Data bus inputs are switching	I <sub>DD7</sub> <sup>1</sup>	2456	1976	1856	1816	mA

- Notes:
1. Value calculated as one module rank in this operating condition; all other module ranks in IDD2P (CKE LOW) mode.
  2. Value calculated reflects all module ranks in this operating condition.



**Table 10: DDR2 I<sub>DD</sub> Specifications and Conditions – 2GB**

Values shown for MT47H128M8 DDR2 SDRAM only and are computed from values specified in the 1Gb (128 Meg x 8) component data sheet

Parameter	Symbol	-80E/ -800	-667	-53E	-40E	Units	
<b>Operating one bank active-precharge current:</b> $t_{CK} = t_{CK} (I_{DD})$ , $t_{RC} = t_{RC} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MIN} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are switching; Data bus inputs are switching	$I_{DD0}^1$	776	735	616	616	mA	
<b>Operating one bank active-read-precharge current:</b> $I_{OUT} = 0\text{mA}$ ; BL = 4, CL = CL ( $I_{DD}$ ), AL = 0; $t_{CK} = t_{CK} (I_{DD})$ , $t_{RC} = t_{RC} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MIN} (I_{DD})$ , $t_{RCD} = t_{RCD} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are switching; Data pattern is same as $I_{DD4W}$	$I_{DD1}^1$	936	856	816	776	mA	
<b>Precharge power-down current:</b> All device banks idle; $t_{CK} = t_{CK} (I_{DD})$ ; CKE is LOW; Other control and address bus inputs are stable; Data bus inputs are floating	$I_{DD2P}^2$	112	112	112	112	mA	
<b>Precharge quiet standby current:</b> All device banks idle; $t_{CK} = t_{CK} (I_{DD})$ ; CKE is HIGH, S# is HIGH; Other control and address bus inputs are stable; Data bus inputs are floating	$I_{DD2Q}^2$	800	640	640	560	mA	
<b>Precharge standby current:</b> All device banks idle; $t_{CK} = t_{CK} (I_{DD})$ ; CKE is HIGH, S# is HIGH; Other control and address bus inputs are switching; Data bus inputs are switching	$I_{DD2N}^2$	800	640	640	560	mA	
<b>Active power-down current:</b> All device banks open; $t_{CK} = t_{CK} (I_{DD})$ ; CKE is LOW; Other control and address bus inputs are stable; Data bus inputs are floating	$I_{DD3P}^2$	Fast PDN exit MR[12] = 0	640	480	480	480	mA
		Slow PDN exit MR[12] = 1	160	160	160	160	
<b>Active standby current:</b> All device banks open; $t_{CK} = t_{CK} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MAX} (I_{DD})$ , $t_{RP} = t_{RP} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Other control and address bus inputs are switching; Data bus inputs are switching	$I_{DD3N}^2$	960	880	720	640	mA	
<b>Operating burst write current:</b> All device banks open; Continuous burst writes; BL = 4, CL = CL ( $I_{DD}$ ), AL = 0; $t_{CK} = t_{CK} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MAX} (I_{DD})$ , $t_{RP} = t_{RP} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are switching; Data bus inputs are switching	$I_{DD4W}^1$	1336	1136	1056	896	mA	
<b>Operating burst read current:</b> All device banks open; Continuous burst read, $I_{OUT} = 0\text{mA}$ ; BL = 4, CL = CL ( $I_{DD}$ ), AL = 0; $t_{CK} = t_{CK} (I_{DD})$ , $t_{RAS} = t_{RAS} \text{ MAX} (I_{DD})$ , $t_{RP} = t_{RP} (I_{DD})$ ; CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are switching; Data bus inputs are switching	$I_{DD4R}^1$	1336	1136	1056	896	mA	
<b>Burst refresh current:</b> $t_{CK} = t_{CK} (I_{DD})$ ; REFRESH command at every $t_{RFC} (I_{DD})$ interval; CKE is HIGH, S# is HIGH between valid commands; Other control and address bus inputs are switching; Data bus inputs are switching	$I_{DD5}^2$	3760	3440	3360	3280	mA	
<b>Self refresh current:</b> CK and CK# at 0V; CKE $\leq 0.2\text{V}$ ; Other control and address bus inputs are floating; Data bus inputs are floating	$I_{DD6}^2$	112	112	112	112	mA	



# 1GB, 2GB (x64, DR) 200-Pin DDR2 SDRAM SODIMM I<sub>DD</sub> Specifications

**Table 10: DDR2 I<sub>DD</sub> Specifications and Conditions – 2GB (Continued)**

Values shown for MT47H128M8 DDR2 SDRAM only and are computed from values specified in the 1Gb (128 Meg x 8) component data sheet

Parameter	Symbol	-80E/ -800	-667	-53E	-40E	Units
<b>Operating bank interleave read current:</b> All device banks interleaving reads; I <sub>OUT</sub> = 0mA; BL = 4, CL = CL (I <sub>DD</sub> ), AL = t <sub>RCD</sub> (I <sub>DD</sub> ) - 1 × t <sub>CK</sub> (I <sub>DD</sub> ); t <sub>CK</sub> = t <sub>CK</sub> (I <sub>DD</sub> ), t <sub>RC</sub> = t <sub>RC</sub> (I <sub>DD</sub> ), t <sub>RRD</sub> = t <sub>RRD</sub> (I <sub>DD</sub> ), t <sub>RCD</sub> = t <sub>RCD</sub> (I <sub>DD</sub> ); CKE is HIGH, S# is HIGH between valid commands; Address bus inputs are stable during deselects; Data bus inputs are switching	I <sub>DD7</sub> <sup>1</sup>	2736	2296	2216	2136	mA

## Serial Presence-Detect

For the latest SPD data, refer to Micron's SPD page: [www.micron.com/SPD](http://www.micron.com/SPD).

**Table 11: SPD EEPROM Operating Conditions**

Parameter/Condition	Symbol	Min	Max	Units
Supply voltage	$V_{DDSPD}$	1.7	3.6	V
Input high voltage: logic 1; All inputs	$V_{IH}$	$V_{DDSPD} \times 0.7$	$V_{DDSPD} + 0.5$	V
Input low voltage: logic 0; All inputs	$V_{IL}$	-0.6	$V_{DDSPD} \times 0.3$	V
Output low voltage: $I_{OUT} = 3\text{mA}$	$V_{OL}$	-	0.4	V
Input leakage current: $V_{IN} = \text{GND to } V_{DD}$	$I_{LI}$	0.1	3	$\mu\text{A}$
Output leakage current: $V_{OUT} = \text{GND to } V_{DD}$	$I_{LO}$	0.05	3	$\mu\text{A}$
Standby current	$I_{SB}$	1.6	4	$\mu\text{A}$
Power supply current, READ: SCL clock frequency = 100 kHz	$I_{CCR}$	0.4	1	mA
Power supply current, WRITE: SCL clock frequency = 100 kHz	$I_{CCW}$	2	3	mA

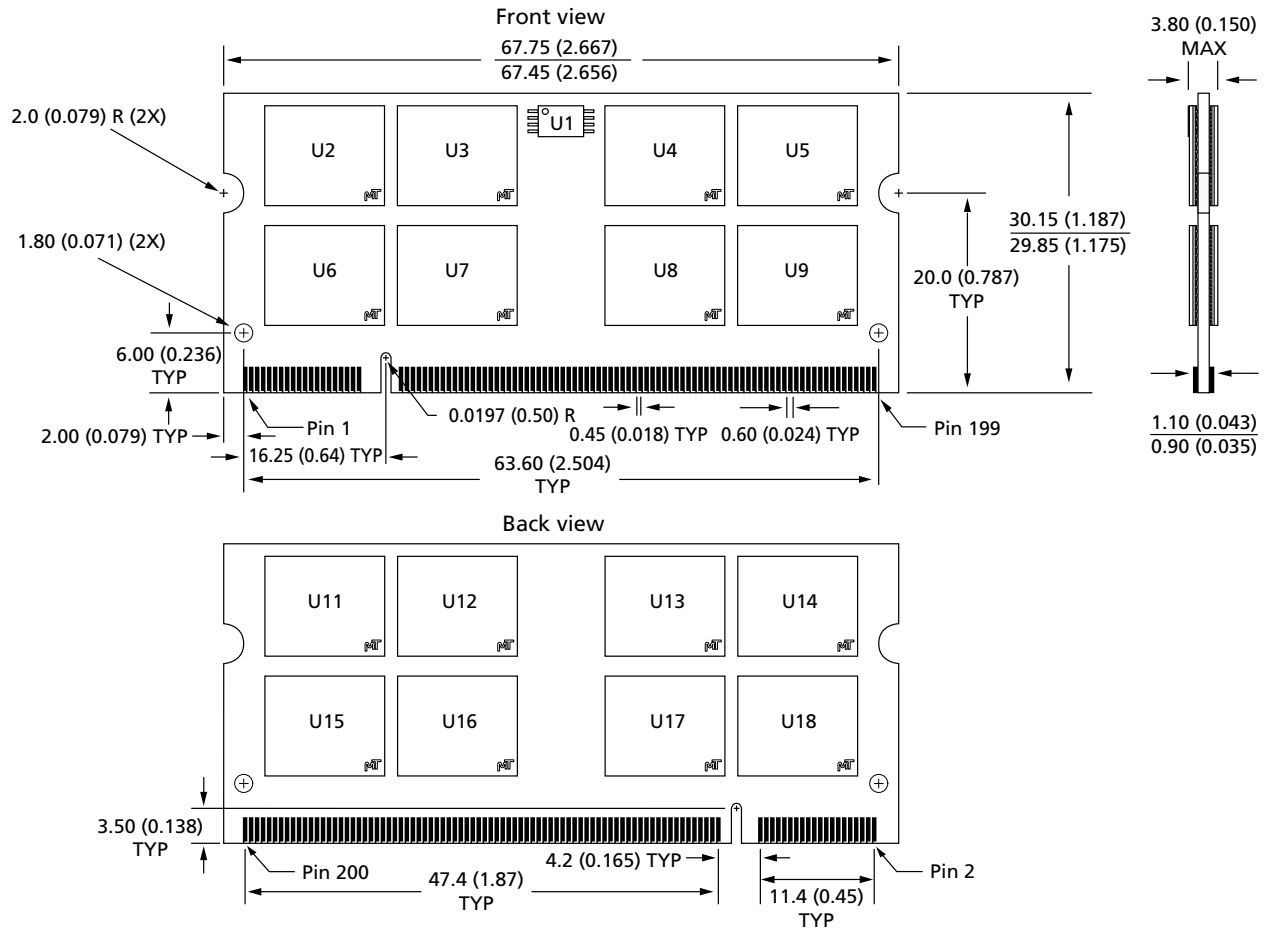
**Table 12: SPD EEPROM AC Operating Conditions**

Parameter/Condition	Symbol	Min	Max	Units	Notes
SCL LOW to SDA data-out valid	$t_{AA}$	0.2	0.9	$\mu\text{s}$	1
Time bus must be free before a new transition can start	$t_{BUF}$	1.3	-	$\mu\text{s}$	
Data-out hold time	$t_{DH}$	200	-	ns	
SDA and SCL fall time	$t_F$	-	300	ns	2
SDA and SCL rise time	$t_R$	-	300	ns	2
Data-in hold time	$t_{HD:DAT}$	0	-	$\mu\text{s}$	
Start condition hold time	$t_{HD:STA}$	0.6	-	$\mu\text{s}$	
Clock HIGH period	$t_{HIGH}$	0.6	-	$\mu\text{s}$	
Noise suppression time constant at SCL, SDA inputs	$t_{\eta}$	-	50	$\mu\text{s}$	
Clock LOW period	$t_{LOW}$	1.3	-	$\mu\text{s}$	
SCL clock frequency	$t_{SCL}$	-	400	kHz	
Data-in setup time	$t_{SU:DAT}$	100	-	ns	
Start condition setup time	$t_{SU:STA}$	0.6	-	$\mu\text{s}$	3
Stop condition setup time	$t_{SU:STO}$	0.6	-	$\mu\text{s}$	
WRITE cycle time	$t_{WRC}$	-	10	ms	4

- Notes:
1. To avoid spurious start and stop conditions, a minimum delay is placed between SCL = 1 and the falling or rising edge of SDA.
  2. This parameter is sampled.
  3. For a restart condition or following a WRITE cycle.
  4. The SPD EEPROM WRITE cycle time ( $t_{WRC}$ ) is the time from a valid stop condition of a write sequence to the end of the EEPROM internal ERASE/PROGRAM cycle. During the WRITE cycle, the EEPROM bus interface circuit is disabled, SDA remains HIGH due to pull-up resistance, and the EEPROM does not respond to its slave address.

## Module Dimensions

**Figure 3: 200-Pin DDR2 SODIMM**



- Notes:
1. All dimensions are in millimeters (inches); MAX/MIN or typical (TYP) where noted.
  2. The dimensional diagram is for reference only. Refer to the JEDEC MO document for additional design dimensions.

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This data sheet contains minimum and maximum limits specified over the power supply and temperature range set forth herein. Although considered final, these specifications are subject to change, as further product development and data characterization sometimes occur.